

BEST AVAILABLE COPY

PATENT ABSTRACTS OF JAPAN

(11)Publication number : 04-361524

(43)Date of publication of application : 15.12.1992

(51)Int.Cl.

H01L 21/027
B05D 1/40
G03F 7/16
// B05C 11/08

(21)Application number : 03-137774

(71)Applicant : TOSHIBA CORP

TOSHIBA MICRO ELECTRON KK

(22)Date of filing : 10.06.1991

(72)Inventor : IMOTO YUKIO

YOSHIZAKI HAJIME

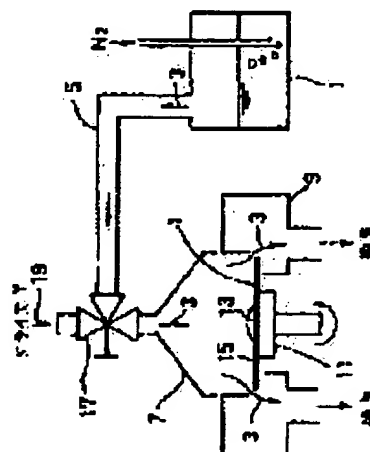
SUGANUMA TATSUMI

(54) RESIST COATING METHOD

(57)Abstract:

PURPOSE: To furnish a resist coating method with which the irregularity in thickness of a resist film can be reduced and concentric circular spots of coating and the like are not generated even when the resist is discharged and applied onto the surface of a rotating wafer in a resist solvent atmosphere.

CONSTITUTION: The inside of a coating cup 9, which is covered by a hood 7, is brought into a resist solvent atmosphere, a wafer 15 is rotated by a spin chuck 11 in the above-mentioned resist solvent atmosphere, and resist 13 is spread on the surface of the wafer 15 by centrifugal force. A three-way valve 17 is controlled with the lapse of time of rotation of the wafer 15, dry air 19 is slowly increased on the contrary of vapor 3 while the vapor 3, coming from a vapor generator 1, is being reduced, and sent to the coating cup 9 covered by the hood 7. As a result, the atmosphere around the wafer is changed from a resist solvent atmosphere to a resist dry atmosphere.



LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]

Copyright (C); 1998,2003 Japan Patent Office